

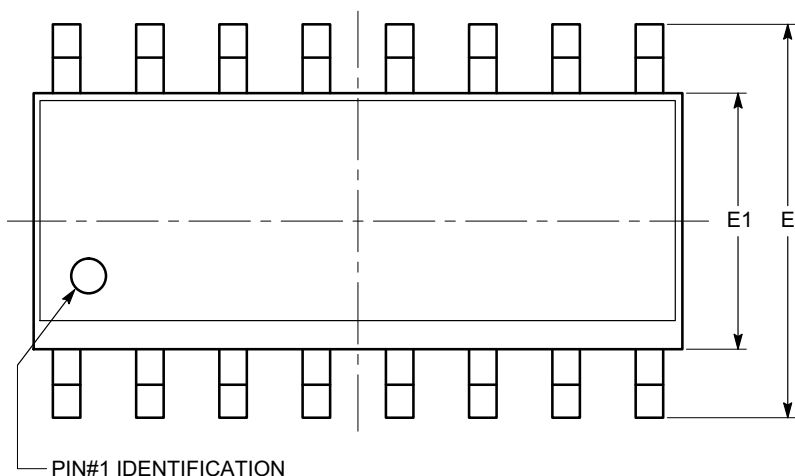
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



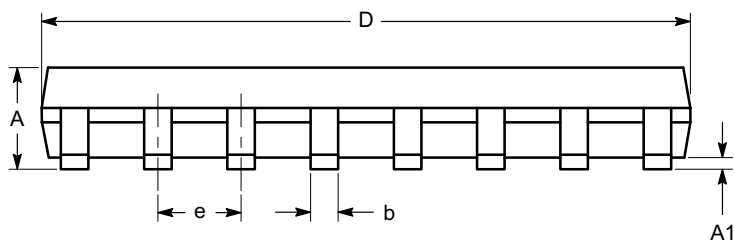
SOIC-16, 150 mils
CASE 751BG-01
ISSUE O

DATE 19 DEC 2008

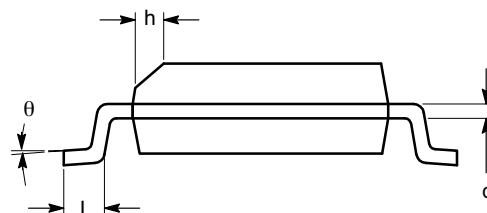


| SYMBOL | MIN | NOM | MAX |
|----------|----------|------|-------|
| A | 1.35 | | 1.75 |
| A1 | 0.10 | | 0.25 |
| b | 0.33 | | 0.51 |
| c | 0.19 | | 0.25 |
| D | 9.80 | 9.90 | 10.00 |
| E | 5.80 | 6.00 | 6.20 |
| E1 | 3.80 | 3.90 | 4.00 |
| e | 1.27 BSC | | |
| h | 0.25 | | 0.50 |
| L | 0.40 | | 1.27 |
| θ | 0° | | 8° |

TOP VIEW



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

| | | |
|-------------------------|---------------------------|--|
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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| REFERENCE: | | |
| DESCRIPTION: | SOIC-16, 150 MILS | PAGE 1 OF 2 |

